

This exploded perspective view illustrates the assembly of a multi-layered electronic device. The components are shown in a disassembled state to reveal their internal structure and alignment. Key features include:

- 900**: The topmost layer, which appears to be a thin, rectangular frame or cover.
- 800**: A middle layer, possibly a substrate or a core, positioned below the top layer.
- 810**: A rectangular frame or border structure, likely part of the middle layer or a separate component.
- 500**: A layer containing a grid of small, rectangular components, possibly solder balls or micro-components, arranged in a regular pattern.
- 700**: A bracketed group of layers including:
  - 710**: A layer with a grid of small, rectangular components, similar to layer 500.
  - 712**: A layer with a grid of small, rectangular components, similar to layer 500.
  - 712a** and **712b**: Sub-layers or regions of the grid.
  - 714** and **716**: Additional layers or components within the bracketed group.
  - 718** and **719**: Small, rectangular components or features on the layers.
- 720**: A bracketed group of layers including:
  - 722a** and **722b**: Sub-layers or regions of a grid.
  - 723a** and **723b**: Small, rectangular components or features on the layers.
  - 724**: A layer with a grid of small, rectangular components, similar to layer 500.
  - 725a** and **725b**: Sub-layers or regions of a grid.
  - 726**: A layer with a grid of small, rectangular components, similar to layer 500.
  - 728**: A layer with a grid of small, rectangular components, similar to layer 500.
  - 730**: A layer with a grid of small, rectangular components, similar to layer 500.
- 820**: The bottommost layer, which appears to be a thin, rectangular frame or cover.

FIG. 2

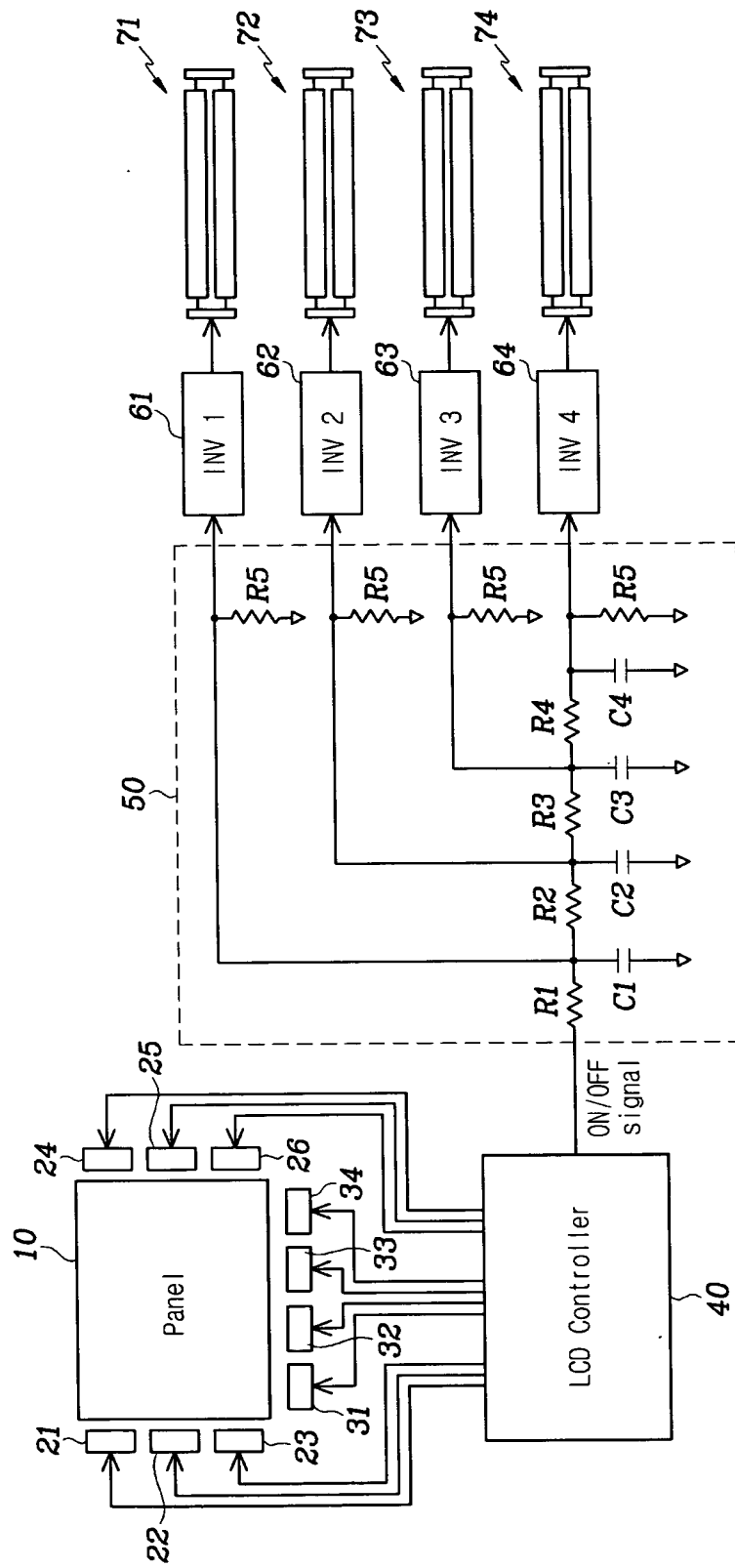


FIG.3

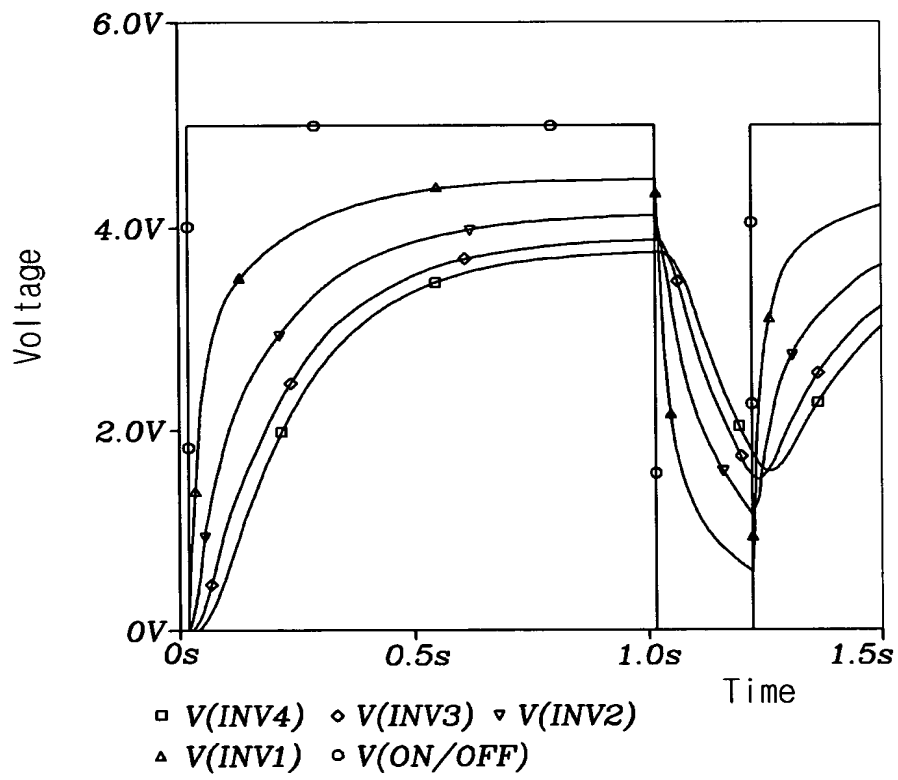


FIG. 4

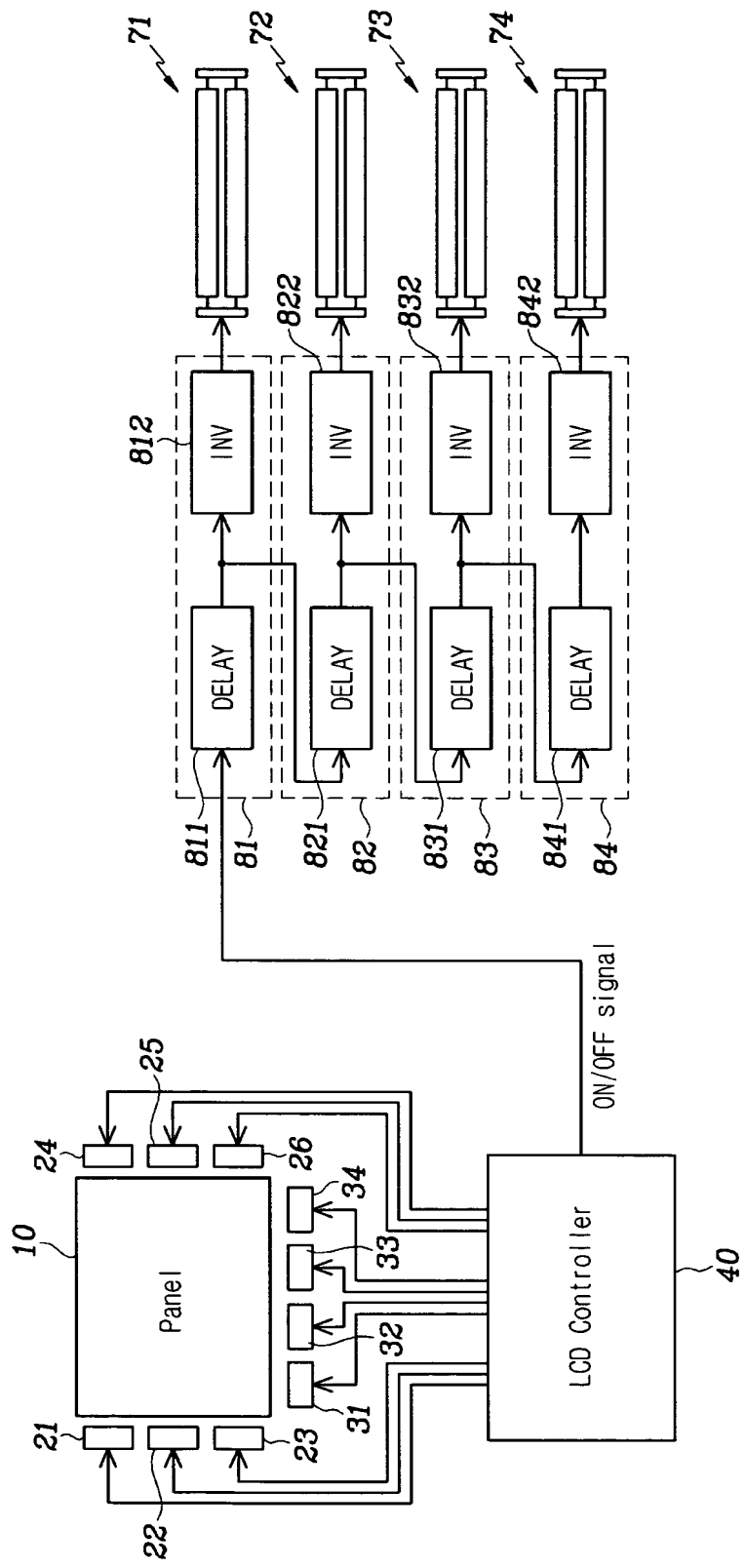


FIG.5

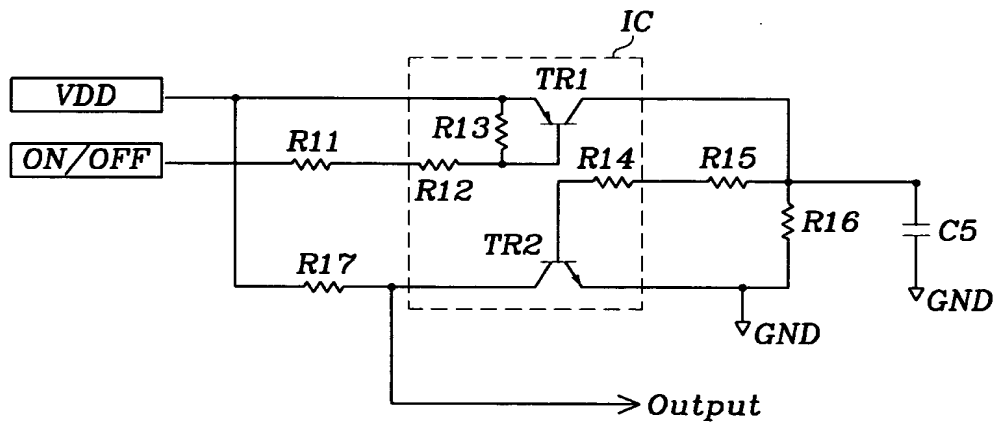


FIG.6

